

**PC400**

## Compact, Surface Mount Type **OPIC Photocoupler**

## ■ Features

1. Opaque, mini-flat package
  2. "Low" output during light emission
  3. Isolation voltage between input and output  
( $V_{iso}$  : 3 750V<sub>rms</sub>)
  4. TTL and LSTTL compatible output
  5. Recognized by UL, file No. E64380

## ■ Applications

1. Hybrid substrate which requires high density mounting
  2. Personal computers, office computers and peripheral equipment
  3. Electronic musical instruments

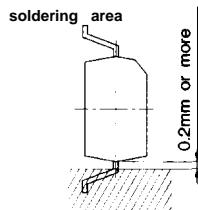
## ■ Package Specifications

Model No.	Package specifications	Diameter of reel	Wafer width
<b>PC400</b>	Taping package(Net:3000pcs.)	Φ 370..	12..
<b>PC400T</b>	Taping package(Net: 750pcs.)	Φ178mm	12mm
<b>PC400Z</b>	Sleeve package(Net: 100Pcs.)		

#### Absolute Maximum Ratings

"OPIC" (Optical IC) is a trademark of the SHARP Corporation.  
An OPIC consists of a light-detecting element and signal-processing circuit integrated onto a single chip.

Parameter		Symbol	Rating	Unit
Input	Forward current	I <sub>F</sub>	50	mA
	Reverse voltage	V <sub>R</sub>	6	v
	Power dissipation	P	70	mW
output	Supply voltage	V <sub>CC</sub>	16	v
	High level output voltage	V <sub>OH</sub>	16	v
	Low level output current	I <sub>OL</sub>	50	mA
	Power dissipation	P <sub>O</sub>	130	mW
Total power dissipation		P <sub>tot</sub>	150	mW
* <sup>1</sup> Isolation voltage		V <sub>iso</sub>	3 750	V <sub>m</sub> ,
Operating temperature		T <sub>opr</sub>	-25 to +85	°C
Storage temperature		T <sub>stg</sub>	-40 to +125	°C
*soldering temperature		T <sub>sol</sub>	260	°C



\*1AC for 1 minute, 40 to 60% RH

\*2 For 10 seconds

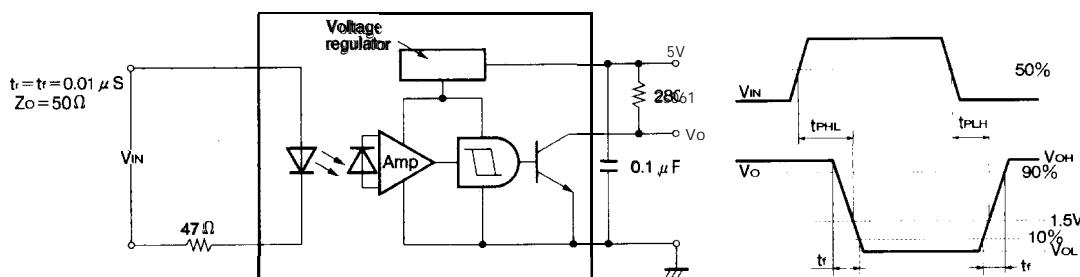
## ■ Electro-optical Characteristics

(Ta = 0 to +70°C unless otherwise specified)

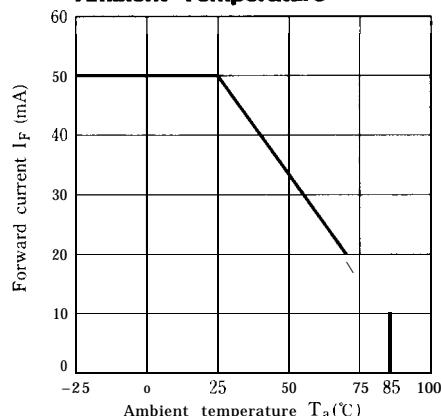
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	V <sub>F</sub>	I <sub>F</sub> =4mA I <sub>F</sub> =0.3mA		1.1	1.4	v
	Reverse current	I <sub>R</sub>	Ta=25°C, V <sub>R</sub> =3V	0.7	1.0		
	Terminal capacitance	C <sub>t</sub>	Ta=25°C, V=0 f=1kHz		30	250	pF
output	Operating supply voltage	V <sub>CC</sub>		3	—	I <sub>S</sub>	V
	Low level output voltage	V <sub>OL</sub>	I <sub>OL</sub> =16mA, V <sub>CC</sub> =5V I <sub>F</sub> =4mA	—	0.2	0.4	V
	High level output current	I <sub>OH</sub>	V <sub>CC</sub> =V <sub>O</sub> =15V, I <sub>F</sub> =0	—	—	100	μA
	Low level supply current	I <sub>CL</sub>	V <sub>CC</sub> =5V, I <sub>F</sub> =4mA	—	2.5	5.0	mA
	High level supply current	I <sub>CH</sub>	V <sub>CC</sub> =5V, I <sub>F</sub> =0	—	1.0	5.0	mA
Transfer characteristics	*3 "H→L" threshold input current	I <sub>FHL</sub>	Ta=25°C, V <sub>CC</sub> =5V R <sub>L</sub> =280Ω V <sub>CC</sub> =5V, R <sub>L</sub> =280Ω		1.1	2.0	mA
	*4 "L→H" threshold input current	I <sub>FLH</sub>	Ta=25°C, V <sub>CC</sub> =5V R <sub>L</sub> =280Ω V <sub>CC</sub> =5V, R <sub>L</sub> =280Ω	0.4	0.8	—	
	Hysteresis	I <sub>FLH</sub> /I <sub>FHL</sub>	V <sub>CC</sub> =5V, R <sub>L</sub> =280Ω	0.5	0.7	0.9	
	Isolation resistance	R <sub>ISO</sub>	Ta=25°C, DC500V 40°C to 60% RH	5x10 <sup>10</sup>	10 <sup>11</sup>		Ω
#Response time	"H→L" propagation delay time	t <sub>PHL</sub>	Ta = 25°C	—	1	3	μs
	"L→H" propagation delay time	t <sub>PLH</sub>	V <sub>CC</sub> =5V, I <sub>F</sub> =4mA	—	2	6	
	Fall time	t <sub>f</sub>	R <sub>L</sub> = 280Ω		0.05	0.5	
	Rise time	t <sub>r</sub>		—	0.1	0.5	

\*3 I<sub>FHL</sub> represents forward current when output goes from high to low.\*4 I<sub>FLH</sub> represents forward current when output goes from low to high.\*5 Hysteresis stands for I<sub>FLH</sub>/I<sub>FHL</sub>.

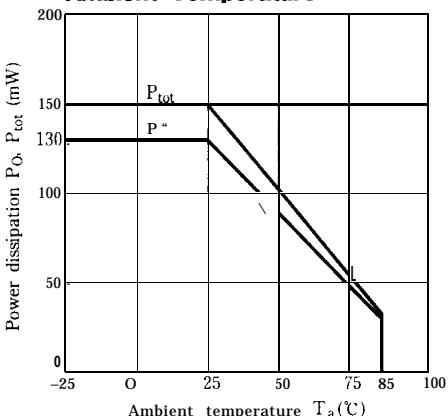
\*6 Test circuit for response time is shown below.



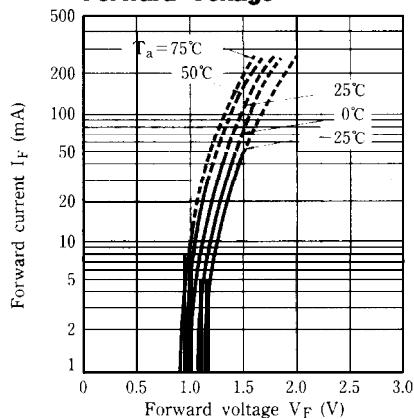
**Fig. 1 Forward Current vs. Ambient Temperature**



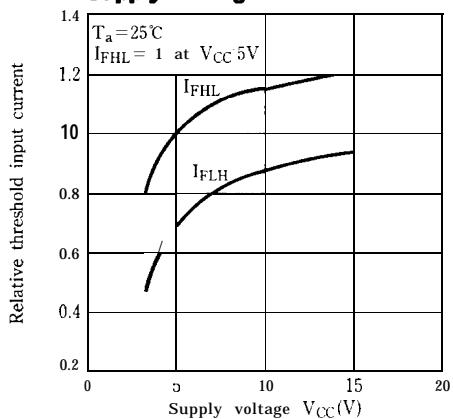
**Fig. 2 Power Dissipation vs. Ambient Temperature**



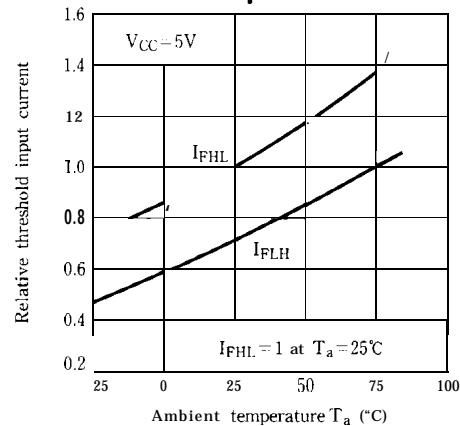
**Fig. 3 Forward Current vs. Forward Voltage**



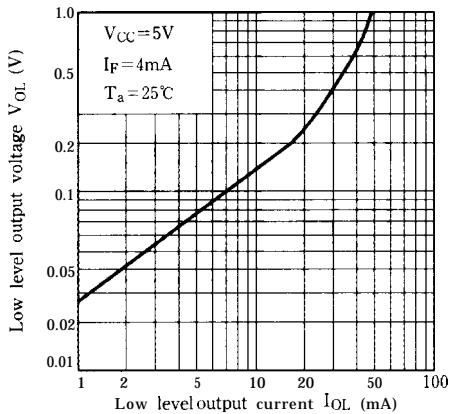
**Fig. 4 Relative Threshold Input Current vs. Supply Voltage**



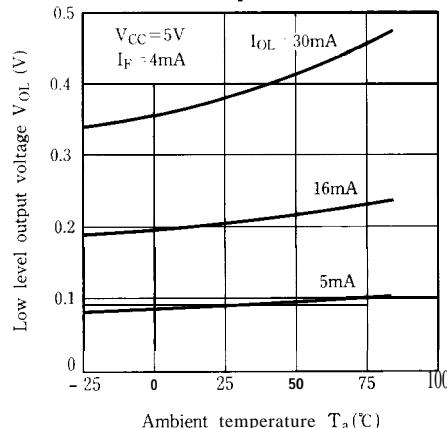
**Fig. 5 Relative Threshold Input Current vs. Ambient Temperature**



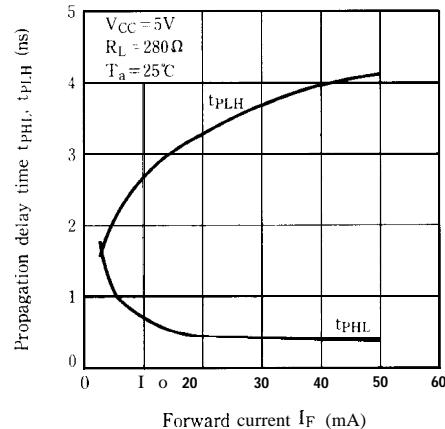
**Fig. 6 Low Level Output Voltage vs. Low Level Output Current**



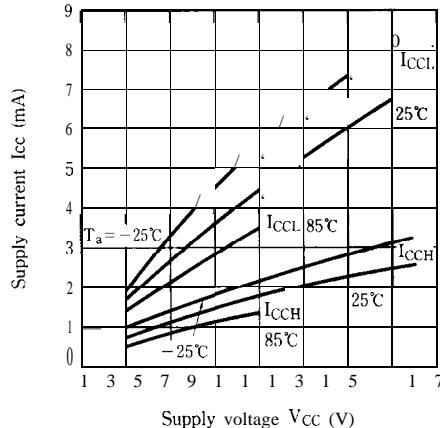
**Fig. 7 Low Level Output Voltage vs. Ambient Temperature**



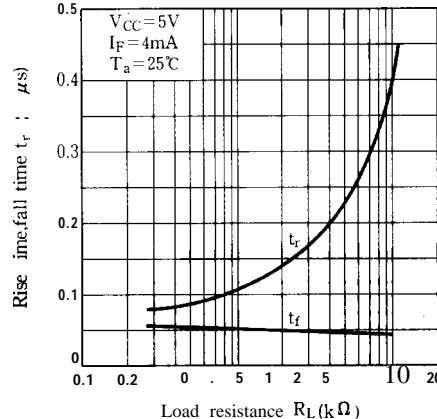
**Fig. 9 Propagation Delay Time vs. Forward Current**



**Fig. 8 Supply Current vs. Supply Voltage**



**Fig. 10 Rise Time, Fall Time vs. Load Resistance**



## ■ Precautions for Use

- (1) It is recommended that a by-pass capacitor of more than  $0.01 \mu F$  be added between  $V_{CC}$  and GND near the device in order to stabilize power supply line.
- (2) Handle this product the same as with other integrated circuits against static electricity.
- (3) As for other general cautions, refer to the chapter "Precautions for Use" (Page 78 to 93).